

METHOD FOR MAKING SUPPORT STRUCTURE FOR PROBING DEVICE

BACKGROUND OF THE INVENTION

1. Field of the Invention

5 The present invention relates to a support structure for a probing device and more particularly, to a method for making a support structure for a probing device.

2. Description of the Related Art

 It is the market trend to provide a space transformer having a thin thickness for probing device. After several times in IC test, the space transformer may be
10 deformed, or may have dentations therein, leading to poor contact or disconnection between the space transformer and the probes.

 Taiwan Patent publication No. 201307851, which is published on February 16, 2013, discloses a probing device (hereinafter referred to as “Prior Art 1”). Referring to the appendix FIGS. 1A and 1B, which correspond to FIGS. 2A and 2B of
15 Prior Art 1 respectively, the detailed structure between the reinforcing board and the space transformer of the probing device is shown.

 As illustrated in FIG. 1A, the probing device **20** comprises a circuit board **22**, a reinforcing board **28**, a space transformer **24**, and a probe module **26**. The circuit board **22**, the reinforcing board **28** and the space transformer **24** are stacked up and
20 electrically connected with one another. The probe module **26** comprises a plurality of probes **262**. The probe module **26** is mounted on the space transformer **24**, and electrically connected with the space transformer **24** and then the circuit board **22**. Thus, test signals received by the probes **262** can be transmitted through the space transformer **24** and the reinforcing board **28** to the circuit board **22** for subsequent
25 analysis. When the probing device **20** is operated to conduct a testing task, the probes

262 of the probe module 26 are kept in contact with the device under test (DUT), which is not shown in the drawings. At this time, the device under test imparts a reaction force to the probes 262, causing the probes 262 to exert a force **F2** to the space transformer 24 (see FIG. 1B).

5 Further, as illustrated in FIG. 1B, in order to prevent the space transformer 24 from being deformed by the force **F2**, the reinforcing board 28 is configured to provide multiple protruding portions 283. The top edges of the protruding portions 283 are stopped against the space transformer 24. Further, every protruding portion 283 defines an accommodation space 282 that accommodates one respective first solder ball 241.

10 Because the space transformer 24 is supported by the protruding portions 283 and the first solder balls 241, the space transformer 24 will not be forced by the force **F2** to deform. Further, it is disclosed in Prior Art 1 that the protruding portions 283 may be formed on the space transformer 24, or simultaneously formed on the reinforcing board 28 and the space transformer 24.

15 The protruding portions 283 recited in Prior Art 1 may be formed by machining. However, Prior Art 1 has drawbacks. A first drawback of Prior Art 1 is that the protruding portions 283 are formed by cutting a thin board member (i.e., the reinforcing board 28 or the space transformer 24, or both of them) into shape. However, because the space transformer provided by manufacturer has a thin thickness,

20 machining the space transformer can cause it to break. A second drawback of Prior Art 1 is that the soldering points of the space transformer 24, which are configured corresponding to the pattern of the contacts of the DUT, are not arranged on one same straight line, and thus, it is difficult to apply a machining process to the thin board in a non-linear manner. A third drawback of Prior Art 1 is that the protruding portions 283

25 are disposed in flush with the outer surface of the reinforcing board 28, and thus, it is

difficult to discharge the waste gas produced when the solder balls are soldered.

Further, Taiwan Utility Model patent No. M442506, which is published on December 1, 2012, discloses a probing device (hereinafter referred to as “Prior Art 2”). As illustrated in the appendix FIG. 2, which corresponds to FIG. 4A of Prior Art 2, a perspective view of a reinforcing board of a probing device of Prior Art 2 is disclosed. As shown in FIG. 2, the reinforcing board of the probing device is configured having a plurality of first gas guiding grooves **286** and a plurality of second gas guiding grooves **288** denoted by the imaginary lines. The first gas guiding grooves **286** and second gas guiding grooves **288** enable the waste gas produced upon soldering of the solder balls to be discharged out of the reinforcing board. Prior Art 2 can eliminate the third drawback of the aforesaid Prior Art 1. However, because the first gas guiding grooves **286** and the second gas guiding grooves **288** are made by machining (milling process), Prior Art 2 still cannot eliminate the aforesaid first and second drawbacks.

Furthermore, Taiwan Utility Model patent No. M451544, which is published on April 21, 2013, discloses a probing device (hereinafter referred to as “Prior Art 3”). As illustrated in the appendix FIG. 3, which corresponds to FIG. 3D of Prior Art 3, a buffer block **25** is formed on a space transformer **24** of a probing device of Prior Art 3. This buffer block **25** has four gas guiding grooves **252** formed on the top surface thereof for guiding out produced waste gas in the soldering process. Prior Art 3 can eliminate the third drawback of the aforesaid Prior Art 1. However, because the gas guiding grooves **252** are formed on the buffer block **25** by machining, Prior Art 3 still cannot eliminate the aforesaid first and second drawbacks.

Thus, the probing devices of the aforesaid various prior arts are still not satisfactory in function, and therefore, how to effectively solve the aforesaid problems is one of the important research and development topics, and has also become an

object in need of improvement.

SUMMARY OF THE INVENTION

The present invention has been accomplished in view of the above-noted circumstances. It is one objective of the present invention to provide a method for
5 making a support structure for a probing device, which prevents the thin space transformer from being curved by an external force, thereby improving the flatness of the space transformer and prolonging the lifespan thereof.

It is another objective of the present invention to provide a method for making a support structure for probing device, which effectively discharges the
10 produced waste gas upon soldering the solder balls.

To achieve these and other objectives of the present invention, a method for making a support structure for a probing device provided by the present invention comprises the steps of:

a) providing a substrate, a carrier for packaging an integrated circuit chip, a
15 plurality of photoresist support blocks made by lithography, and a plurality of solder balls, wherein the substrate comprises a plurality of first internal conductive lines; the carrier comprises a plurality of second internal conductive lines; the carrier has a thickness less than 2 mm; the photoresist support blocks and the solder balls are disposed between the substrate and the carrier; the photoresist support blocks are
20 separately arranged; at least one of the photoresist support blocks is disposed between two adjacent solder balls; and

b) soldering the carrier and the substrate with the solder balls by reflow soldering to electrically connect the first internal conductive lines with the second internal conductive lines respectively.

25 Other advantages and features of the present invention will be fully

understood by reference to the following specification in conjunction with the accompanying drawings, in which like reference signs denote like components of structure.

Further scope of applicability of the present invention will become apparent
5 from the detailed description given hereinafter. However, it should be understood that the detailed description and specific examples, while indicating preferred embodiments of the present invention, are given by way of illustration only, since various changes and modifications within the spirit and scope of the present invention will become apparent to those skilled in the art from this detailed description.

10 **BRIEF DESCRIPTION OF THE DRAWINGS**

FIG. 1A illustrates a probing device according to Prior Art 1.

FIG. 1B illustrates the structure between the reinforcing board and the space transformer of the probing device shown in FIG. 1A.

FIG. 2 is a perspective view of a reinforcing board of a probing device
15 according to Prior Art 2.

FIG. 3 illustrates a buffer block located on a space transformer of a probing device according to Prior Art 3.

FIG. 4 is a schematic view illustrating a support structure used in a probing device in accordance with a first embodiment of the present invention.

20 FIG. 5 is a schematic top view of the substrate shown in FIG. 4.

FIG. 6 is a schematic view illustrating a support structure used in a probing device in accordance with a second embodiment of the present invention.

FIG. 7 is a schematic view illustrating a support structure used in a probing

device in accordance with a third embodiment of the present invention.

FIGS. 8A—8F illustrate various alternate forms of the photoresist support blocks of the support structure for the probing device in accordance with the present invention.

5 DETAILED DESCRIPTION OF THE INVENTION

It is to be understood that the drawings disclosed in the present invention are given by way of schematically illustrating the known, common elements and/or structural features of the present invention only; therefore, they are not, or need not to be, sketched according to actual dimension.

10 In view of the drawbacks of the prior art designs that using a machining method to make protruding portions for support purposes is difficult to process the thin board in a non-linear manner and can easily cause the thin board to break, the present invention employs lithography to form a photoresist on a thin board in a predetermined pattern, and thus support blocks can be pre-formed on a thin board (such as space
15 transformer), preventing deformation of the thin board upon receiving a force. Further, the present invention does not need to create gas guiding grooves, and produced waste gas during soldering of the solder balls can be effectively discharged.

Embodiment I:

Referring to FIG. 4, a support structure **100** used in a probing device **10** in
20 accordance with a first embodiment of the present invention is schematically shown. FIG. 5 is a schematic top view of the substrate **200** shown in FIG. 4. As illustrated in FIGS. 4 and 5, the probing device **10** comprises a support structure **100**, and at least

one probe module **700**. As illustrated in FIG. 4, the support structure **100** is used in the probing device **10**, comprising a substrate **200**, a thin carrier **300** (in this embodiment, the carrier **300** is a space transformer **300**), a plurality of solder balls **400**, and a plurality of photoresist support blocks **500**. The method for making the support structure **100** includes step a) and step b). Step a) is to provide the aforesaid substrate **200**, carrier **300**, solder balls **400** and photoresist support blocks **500** in a specific way. Step b) is to solder the carrier **300** and the substrate **200** with the solder balls **400** by a process of reflow soldering. The method for making the support structure **100** and the support structure **100** thus obtained will be described hereinafter in detail.

10 The substrate **200** is provided at an inside thereof with a plurality of first internal conductive lines **210**. The space transformer **300** is provided at an inside thereof with a plurality of second internal conductive lines **310**, and further has a plurality of first conductive contact pads **320**, and a plurality of second conductive contact pads **330**. The first conductive contact pads **320** are separately arranged a first surface of the space transformer **300** that faces toward the probe module **700**. The second conductive contact pads **330** are separately arranged on an opposite second surface of the space transformer **300** that faces toward the substrate **200**. The second internal conductive lines **310** are embedded inside the space transformer **300** with respective two opposite ends thereof respectively electrically connected to the respective first conductive contact pads **320** and the respective second conductive contact pads **330**. The interval **S1** between each two adjacent first conductive contact pads **320** is smaller than the interval **S2** between each two adjacent second conductive

contact pads **330**. The solder balls **400** are separately arranged between the substrate **200** and the space transformer **300**, and respectively electrically connected with the first internal conductive lines **210** and respectively electrically connected with the second internal conductive lines **310** through the respective second conductive contact pads **330**. After reflow soldering in step b), the first internal conductive lines **210** are respectively electrically connected with the second internal conductive lines **310**. The photoresist support blocks **500** are directly pre-formed on the substrate **200** or the space transformer **300** subject to actual demand. Preferably, the photoresist support blocks **500** are directly pre-formed on the space transformer **300**; however, it is not a limitation to the claim scope of the present invention. Thus, the photoresist support blocks **500** are arranged between the substrate **200** and the space transformer **300** and spaced from one another, i.e., the photoresist support blocks **500** are independently separated from one another. Thus, waste gas produced during soldering of the solder balls **400** can be discharged without the need of gas guiding grooves as provided and seen in the prior arts. Further, at least one photoresist support block **500** may be provided between each two adjacent solder balls **400**. However, it is within the scope of the present invention as long as at least one of the photoresist support blocks **500** is located between two adjacent solder balls **400**. It is to be noted that the photoresist support blocks **500** are electrically insulated photoresist support blocks. Further, it is the optimal design that the interval between any two adjacent solder balls **400**, between which at least one photoresist support block **500** is arranged, should not be less than 20 μm . The so-called “interval” in the present invention means the shortest distance

between two adjacent solder balls **400**.

The probe module **700** is mounted to one surface of the space transformer **300** of the support structure **100** that faces toward the device under test (not shown).

The probe module **700** comprises a plurality of probes **710**. The probes **710** have the
5 one ends thereof contacting the first conductive contact pads **320** respectively. Through
the first conductive contact pads **320**, the probes **710** are respectively electrically
connected with the second internal conductive lines **310**, the second conductive contact
pads **330**, the solder balls **400** and the first internal conductive lines **210**. The
respective other ends of the probes **710** are adapted for contacting the device under
10 test.

As described above, the solder balls **400** and the photoresist support blocks
500 are arranged between the substrate **200** and the space transformer **300** in a
staggered manner, thus, when the probes **710** of the probe module **700** contact the
device under test, the solder balls **400** and the photoresist support blocks **500** support
15 the space transformer **300** to bear the reaction force that is fed back by the device
under test, preventing deformation of the space transformer **300**, and thus, the lifespan
of the space transformer **300** is greatly prolonged.

In this first embodiment, as shown in FIG. 4, every photoresist support block
500 is sandwichedly secured between and kept in direct contact with the substrate **200**
20 and the space transformer **300**. Every photoresist support block **500** is kept apart from
every solder ball **400** at a distance, preventing the photoresist support blocks **500** from
interfering with the soldering between the solder balls **400** and the first internal

conductive lines **210** and second internal conductive lines **310**. It is to be noted that the distance between every photoresist support block **500** and every solder ball **400** can be designed subject to actual demand as long as the photoresist support blocks **500** are kept apart from the solder balls **400**. Keeping the photoresist support blocks **500** away
5 from the solder balls **400** at a distance is to avoid interference with signal transmission and to maintain structural integrity of the solder balls **400**. Further, letting the photoresist support blocks **500** touch the solder balls **400** may cause solder leaking, leading to series connection of other two unrelated signals.

Further, the space transformer **300** in the present invention is configured
10 having a multi-layered organic (MLO) structure. The space transformer **300** may be, but not limited to, a carrier for packaging an integrated circuit chip, which usually has a thickness less than 2 mm, or normally, in the range within 0.05 mm to 1 mm. That is to say, the space transformer **300** may be a carrier provided by an IC manufacturer or IC designer for packaging an integrated circuit chip. The solder balls **400** generally
15 refer to the tin paste, tin balls, or other related structures. However, this is not a limitation to the present invention. In this embodiment, the substrate **200** is a printed circuit board; however, it is not limited thereto. In other embodiments, the substrate **200** may be a multi-layered ceramic (MLC) structure, or a combination of a multi-layered ceramic structure and a multi-layered organic structure (MLOC)
20 electrically bonded together by pre-reflow soldering.

It is to be noted that the photoresist support blocks **500** are directly pre-formed of a photoresist on the substrate **200** or the space transformer **300** by

lithography. More specifically, the photoresist support blocks **500** are directly pre-formed on the surface of the carrier **300** that faces toward the substrate **200**, or on the surface of the substrate **200** that faces toward the carrier **300**. More precisely, the photoresist support blocks **500** may be formed by repeatedly depositing photoresist on the substrate **200** or the space transformer **300** to form a photoresist layer having a suitable thickness, and then patterning the photoresist layer to form the desired independent photoresist support blocks **500** on the substrate **200** or the space transformer **300**. By this way, the photoresist support blocks **500** are directly pre-formed on the substrate **200** or the transformer **300**.

Because the photoresist support blocks **500** are made by lithography, they can be formed on the substrate **200** or the space transformer **300** subject to any desired pattern. This means that a non-linear arrangement can be provided without the need of machining the thin space transformer **300**. Because the photoresist support blocks **500** are arranged separately, waste gas produced during soldering of the solder balls **400** can be discharged without the need of creating gas guiding grooves as seen in the prior arts. Because the present invention can overcome the drawbacks of the prior arts, the photoresist support blocks **500** can be freely arranged among multiple solder balls **400** in a periodic or aperiodic manner (see FIG. 5).

For example, if an IC package carrier provided by an IC manufacturer or IC designer is used for the space transformer **300**, the designer can utilize the known information of the allocation of the solder balls **400** on the space transformer **300** to make the photoresist support blocks **500** on the space transformer **300** or the substrate

200 in a staggered manner beyond the locations of the solder balls **400**, keeping the photoresist support blocks **500** away from the solder balls **400** without touching any of the solder balls **400**.

Embodiment II:

5 Referring to FIG. 6, a support structure **101** used in a probing device **11** in accordance with a second embodiment of the present invention is shown. As illustrated in FIG. 6, the support structure **101** in accordance with this second embodiment is substantially similar to the support structure **100** of the aforesaid first embodiment with the exception that the support structure **101** of this second embodiment further
10 comprises a reinforcing board **600**. In the fabrication of the support structure **101**, the step a) further provides a substep of providing this reinforcing board **600**, and setting it in between the substrate **200** and the space transformer **300**. The reinforcing board **600** has a first surface **601** facing toward the space transformer **300**, and an opposing second surface **602** facing toward the substrate **200**. The reinforcing board **600** may be,
15 but not limited to, an aluminum oxide board or silicon nitride board. The reinforcing board **600** is adapted to enhance the overall structural strength of the support structure **101**. Further, because the reinforcing board **600** is an independent structure, it can be pre-made.

 The reinforcing board **600** has a plurality of through holes **610**. The through
20 holes **610** are separately arranged in the reinforcing board **600** corresponding in location to the solder balls **400**, and respectively accommodate the solder balls **400** therein. In this second embodiment, the photoresist support blocks **501** are pre-formed

on the first surface **601** of the reinforcing board **600**, namely on the surface of the reinforcing board **600** that faces toward the space transformer **300**; therefore, every photoresist support block **501** is disposed between the space transformer **300** and the reinforcing board **600**, and kept in contact with them. However, this design is not a
5 limitation to the present invention. Alternately, the photoresist support blocks **501** can be pre-formed on the surface of the space transformer **300** that faces toward the reinforcing board **600**. In this second embodiment, the substrate **200**, the space transformer **300**, the solder balls **400**, the photoresist support blocks **501**, the support structure **101** and the probe module **700** are identical to like parts in the aforesaid first
10 embodiment.

Embodiment III:

Referring to FIG. 7, a support structure **102** used in a probing device **12** in accordance with a third embodiment of the present invention is shown. As illustrated in FIG. 7, the support structure **102** in accordance with this third embodiment is
15 substantially similar to the support structure **101** of the aforesaid second embodiment with the exception that the photoresist support blocks **502** in accordance with this third embodiment are directly pre-formed on the second surface **602** of the reinforcing board **600**, namely on the surface of the reinforcing board **600** facing toward the substrate **200**, and therefore, every photoresist support block **502** is disposed between the
20 substrate **200** and the reinforcing board **600**, and kept in contact with them. However, this design is not a limitation to the present invention. Alternately, the photoresist support blocks **501** can be pre-formed on the surface of the substrate **200** that faces

toward the second surface **602** of the reinforcing board **600**. In this third embodiment, the substrate **200**, the space transformer **300**, the solder balls **400**, the photoresist support blocks **502**, the support structure **102** and the probe module **700** are identical to like parts in the aforesaid first or second embodiment.

5 FIGS. 8A-8F illustrate various alternate forms of the photoresist support blocks of the support structure for being used in a probing device. Because the photoresist support blocks are made by lithography, the shape, size, interval, location and pattern arrangement of the photoresist support blocks can be controlled as expected. It is to be noted that the photoresist support blocks described hereinafter can
10 be used in any of the above-described three embodiments.

With respect to the shape of the photoresist support blocks, the photoresist support blocks can be designed in the form of any geometric shape, such as, but not limited to, rectangular column-shaped photoresist support blocks **500** shown in FIG. 5, cylindrical column-shaped photoresist support blocks **500a** shown in FIG. 8A,
15 L-shaped photoresist support blocks **500L** shown in FIG. 8B, V-shaped photoresist support blocks **500V** shown in FIG. 8C, U-shaped photoresist support blocks **500U** shown in FIG. 8D, or Y-shaped photoresist support blocks **500Y** shown in FIG. 8E.

The shape of the photoresist support blocks can be extended to the left and right sides, or top and bottom sides, of any solder ball **400**. More specifically, if the
20 solder balls **400** can define two paths **P1**, **P2** that perpendicularly intersect with each other, the photoresist support blocks can be simultaneously located in the paths **P1**, **P2**. For example, the L-shaped photoresist support blocks **500L** shown in FIG. 8B, the

V-shaped photoresist support blocks **500V** shown in FIG. 8C, the U-shaped photoresist support blocks **500U** shown in FIG. 8D, or the Y-shaped photoresist support blocks **500Y** shown in FIG. 8E have parts located in the paths **P1**, **P2**, respectively.

In order to enhance the effect of a larger area of support and to reduce the risk of deformation of the space transformer **300**, it is most preferably to maximize the size of the photoresist support blocks **500b** between any two adjacent solder balls **400**, as shown in FIG. 8F. For example, the photoresist support block **500b** may occupy 4/5 or more of the space between two adjacent solder balls **400**. To this end, the photoresist support blocks may be made in the form of a reuleaux curved-edge squad **510**. The reuleaux curved-edge squad **510** has four vertices **511**, four curved edges **512** each connected between two adjacent vertices **511**. This kind of photoresist support block may be arranged in a way that each curved edge **512** faces toward one respective solder ball **400**, such that each curved edge **512** is disposed in proximity to one respective solder ball **400** without physically contacting the solder ball **400**.

With respect to the size of the photoresist support blocks, as illustrated in FIG. 5, all the photoresist support blocks **500** have the same area. More specifically, the side of each photoresist support block **500** facing toward the space transformer **300** or the substrate **200** has the same area. However, this design is not a limitation to the present invention. Alternately, the surfaces of the photoresist support blocks **500** facing toward the space transformer **300** or substrate **200** may be made in at least two different areas.

With respect to the interval between two adjacent photoresist support blocks **500**, as shown in FIG. 5, the interval between each two adjacent photoresist support

blocks **500** can be different. More specifically, at least two different intervals **G1**, **G2** are defined between the photoresist support blocks **500**.

With respect to the locations of the photoresist support blocks, as shown in FIG. 5, the photoresist support blocks **500** are respectively disposed between any two adjacent solder balls **400** that can be longitudinally or transversely arranged in line, or, more particularly, the photoresist support blocks **500c** can be disposed between two adjacent solder balls **400** that are obliquely arranged in line. More specifically speaking, when any four adjacent solder balls **400** define an imaginary quadrilateral **S**, the photoresist support block **500c** may be located or approximately located in a centroid **C** of the imaginary quadrilateral **S**. Further, because the photoresist support blocks are used to support and enable the space transformer **300** having a thin thickness to resist the reaction force transmitted from the DUT through the probes **710** of the probe module **700**, the photoresist support blocks shall be distributed at least in a region corresponding to the distributed region of the probes **710** of the probe module **700**, or preferably at a region corresponding to the location of the probe module **700**, or more preferably at a region substantially corresponding to the whole area of the space transformer **300**. For example, as shown in FIGS. 4, the photoresist support blocks **500** are distributed between the space transformer **300** and the substrate **200** in a region not only corresponding to the location of the probe module **700** but also covering almost the whole area of the space transformer **300**. By this design, the photoresist support blocks **500** can provide a full support to the space transformer **300** for preventing the space transformer **300** from being deformed when the space

transformer **300** receives the reaction force.

With respect to the pattern arrangement of the photoresist support blocks, as shown in FIG. 5, the photoresist support blocks **500** can be arranged in an array or approximately like an array, or any other suitable arrangement. More specifically, the photoresist support blocks can be arranged in a multi-row pattern. In the multi-row pattern, there are multiple rows **R** (for example, 4 rows). Any two adjacent rows define therebetween a gas guiding path **520**. Because the photoresist support blocks **500** are separately arranged, the gas guiding paths **520** can extend in the longitudinal direction, in the transverse direction, or in a non-linear direction, having the solder balls **400** located therein. Thus, when the solder balls **400** are soldered, waste gas thus produced can be discharged to the outside. Because the photoresist support blocks **500** are made by lithography, the photoresist support blocks **500** that define the gas guiding paths **520** need not to be located on one same straight line. Therefore, the gas guiding paths **520** can be configured to extend in a non-linear manner, or, the gas guiding paths **520** can be configured having two different widths **W1**, **W2**. However, it is to be noted that the present invention is not limited to aforesaid arrangement.

Further, because the photoresist support blocks **500** are made by lithography, if the solder balls **400** of two different diameters **D1**, **D2** are arranged in one same gas guiding path **520**, the arrangement of the photoresist support blocks **500** can be easily designed to keep away from the solder balls **400** having different sizes.

Although particular embodiments of the present invention have been described in detail for purposes of illustration, various modifications and

enhancements may be made without departing from the spirit and scope of the present invention. Accordingly, the present invention is not to be limited except as by the appended claims.

WHAT IS CLAIMED IS:

1. A method for making a support structure for a probing device, comprising the steps of:

a) providing a substrate having a plurality of first internal conductive lines, a carrier having a plurality of second internal conductive lines and a thickness less than 2 mm for packaging an integrated circuit chip, a plurality of photoresist support blocks made by lithography, and a plurality of solder balls in a way that the photoresist support blocks and the solder balls are disposed between the substrate and the carrier, the photoresist support blocks are separately arranged, and at least one of the photoresist support blocks is disposed between two adjacent said solder balls; and

b) soldering the carrier and the substrate with the solder balls by reflow soldering to electrically connect the first internal conductive lines with the second internal conductive lines respectively.

2. The method as claimed in claim 1, wherein the at least one of the photoresist support blocks is disposed between two adjacent said solder balls in a way that the two adjacent said solder balls define therebetween an interval larger than 20 μm .

3. The method as claimed in claim 1, wherein the photoresist support blocks have a shape of cylindrical column or rectangular column.

4. The method as claimed in claim 1, wherein the surfaces of the photoresist support blocks that face toward the carrier or the substrate have at least two different areas.

5. The method as claimed in claim 1, wherein the carrier is a space transformer.

5 6. The method as claimed in claim 1, wherein the substrate is selected from the group consisting of a printed circuit board, a board having a multi-layered ceramic structure, and a board having a multi-layered ceramic structure and a multi-layered organic structure.

10 7. The method as claimed in claim 1, wherein the step a) further comprises a substep of providing a reinforcing board and disposing the reinforcing board between the substrate and the carrier; the reinforcing board has a plurality of through holes that accommodate the solder balls respectively.

15 8. The method as claimed in claim 7, wherein the photoresist support blocks are directly pre-formed on a first surface or a second surface of the reinforcing board; the first surface of the reinforcing board faces toward the carrier, and the second surface of the reinforcing board faces toward the substrate.

20 9. The method as claimed in claim 1, wherein the photoresist support blocks are directly pre-formed on a surface of the carrier or a surface of the substrate; the surface of the carrier faces toward the substrate, and the surface of the substrate faces toward the carrier.

25 10. The method as claimed in claim 1, wherein the photoresist support blocks

are arranged among the solder balls in an aperiodic manner.

11. The method as claimed in claim 1, wherein each two adjacent said photoresist support blocks define therebetween an interval, and the intervals among
5 said photoresist support blocks are partially the same.

12. The method as claimed in claim 1, wherein the photoresist support blocks are arranged in a pattern having multiple rows; any two adjacent rows of the photoresist support blocks in the pattern define a gas guiding path in which one or
10 more of the solder balls are located; at least one of the gas guiding paths has at least two different widths.

13. The method as claimed in claim 12, wherein at least one of the gas guiding paths extends in a non-linear manner.
15

14. The method as claimed in claim 12, wherein the solder balls that are located in one of the gas guiding paths have at least two different diameters.

15. The method as claimed in claim 1, wherein four adjacent said solder balls
20 define an imaginary quadrilateral; at least one of the photoresist support blocks is located in a centroid of the imaginary quadrilateral.

16. The method as claimed in claim 15, wherein the at least one of the photoresist support blocks that is located in the centroid of the imaginary quadrilateral
25 is a reuleaux curved-edge squad having four vertices and four curved edges each

connected between two adjacent said vertices; each said curved edge faces toward one respective said solder ball.

17. The method as claimed in claim 1, wherein at least one of the photoresist
5 support blocks has an L-shaped, V-shaped, U-shaped or Y-shaped profile.

18. The method as claim in claim 1, wherein the carrier has a first surface on
which a probe module is disposed, and a second surface that is opposite to the first
surface and faces toward the substrate; the photoresist support blocks are separately
10 arranged at least in a region corresponding to the probe module.